

PHP20NQ20T-VB Datasheet N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)			
200	0.110 at V _{GS} = 10 V	30			

G D S

Top View

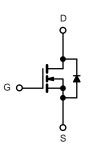
DRAIN connected to TAB

FEATURES

- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V _{DS}	200					
Gate-Source Voltage	V _{GS}	± 20	V				
Continuous Durin Querent (T. 175 °C)b	T _C = 25 °C		30				
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 125 °C	I _D	15				
Pulsed Drain Current	I _{DM}	70	А				
Continuous Source Current (Diode Conduction)	۱ _S	12					
Avalanche Current	I _{AS}	12					
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ			
Movimum Dougr Dissinction	T _C = 25 °C	P _D	126 ^b	w			
Maximum Power Dissipation	T _A = 25 °C	ГD	3 ^a				
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 175	°C				

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
	t ≤ 10 s	R _{thJA}	15	18	°C/W		
Junction-to-Ambient ^a	Steady State		40	50			
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1			

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.





Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$			50	μA	
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.110	0.125		
	D	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$		0.120 0.140		0	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}, \text{ T}_{J} = 175 \text{ °C}$		0.130	0.150	Ω	
		V _{GS} = 4.5 V, I _D = 3 A		0.132	0.152		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		35		S	
Dynamic ^a							
Input Capacitance	C _{iss}			1800		pF	
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, F = 1 MHz		180			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Qg			34	51		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_{D} = 3 A		8		nC	
Gate-Drain Charge ^c	Q _{gd}			12		1	
Gate Resistance	R _g		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	V_{DD} = 100 V, R _L = 5.2 Ω		50	75	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ 3 A, V_{GEN} = 10 V, R_g = 2.5 Ω		30	45		
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Chara	acteristics (1	Γ _C = 25 °C)			1		
Pulsed Current	I _{SM}				30	А	
Diode Forward Voltage ^b	V _{SD}	I _F = 3 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 3 A, dl/dt = 100 A/μs		180	250	ns	

Notes:

a. Guaranteed by design, not subject to production testing.

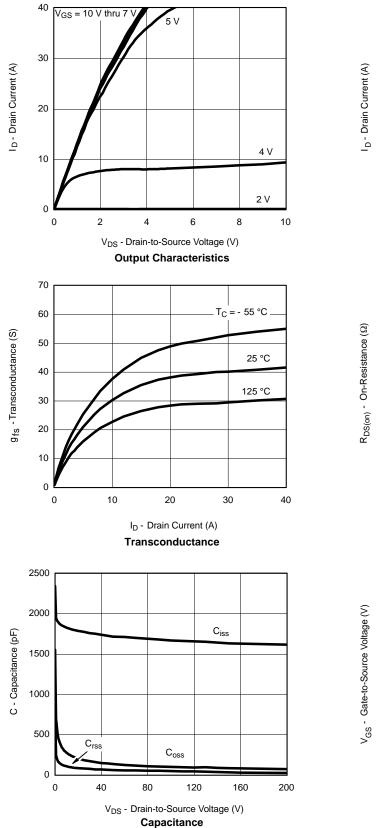
b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

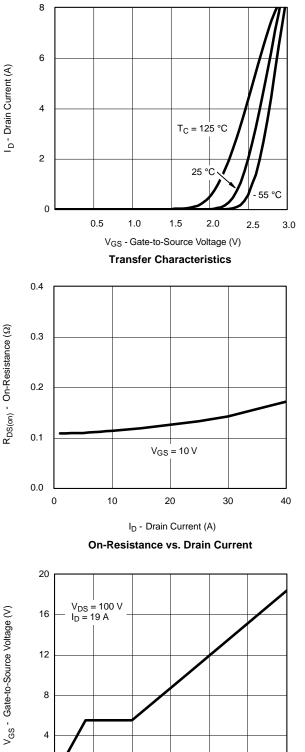
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.









Qg - Total Gate Charge (nC)

Gate Charge

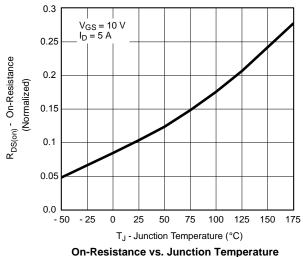


T_J = 25 °C

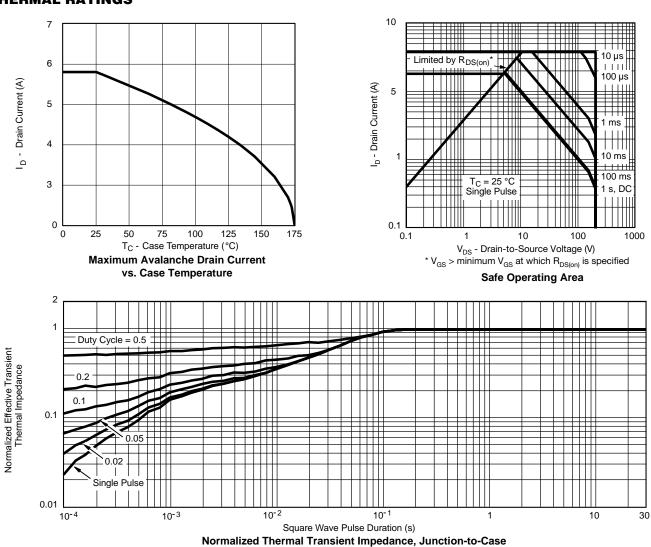
0.9

1.2

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



THERMAL RATINGS



100

10

1

0

0.3

T_J = 150 °C

0.6

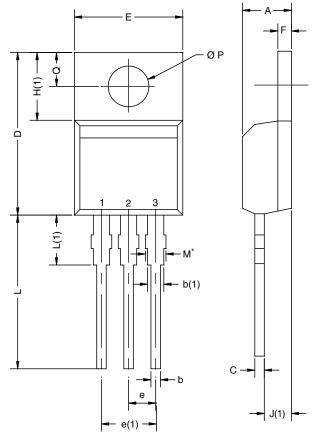
Source-Drain Diode Forward Voltage

V_{SD} - Source-to-Drain Voltage (V)

I_S - Source Current (A)



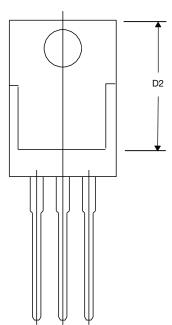
TO-220AB



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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